

Electronic Patent Application Fee Transmittal

Application Number:	10623679			
Filing Date:	22-Jul-2003			
Title of Invention:	Resist pattern thickening material, resist pattern and process for forming the same, and semiconductor device and process for manufacturing the same			
First Named Inventor/Applicant Name:	Koji Nozaki			
Filer:	Shuji Yoshizaki			
Attorney Docket Number:	030891			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1202	1	52	52
Independent claims in excess of 3	1201	1	220	220
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490
Miscellaneous:				
Total in USD (\$)				762